



TSMC RUN SCHEDULE 2026

November 21, 2025 – v1.0



MINI@SIC RUN SCHEDULE 2026

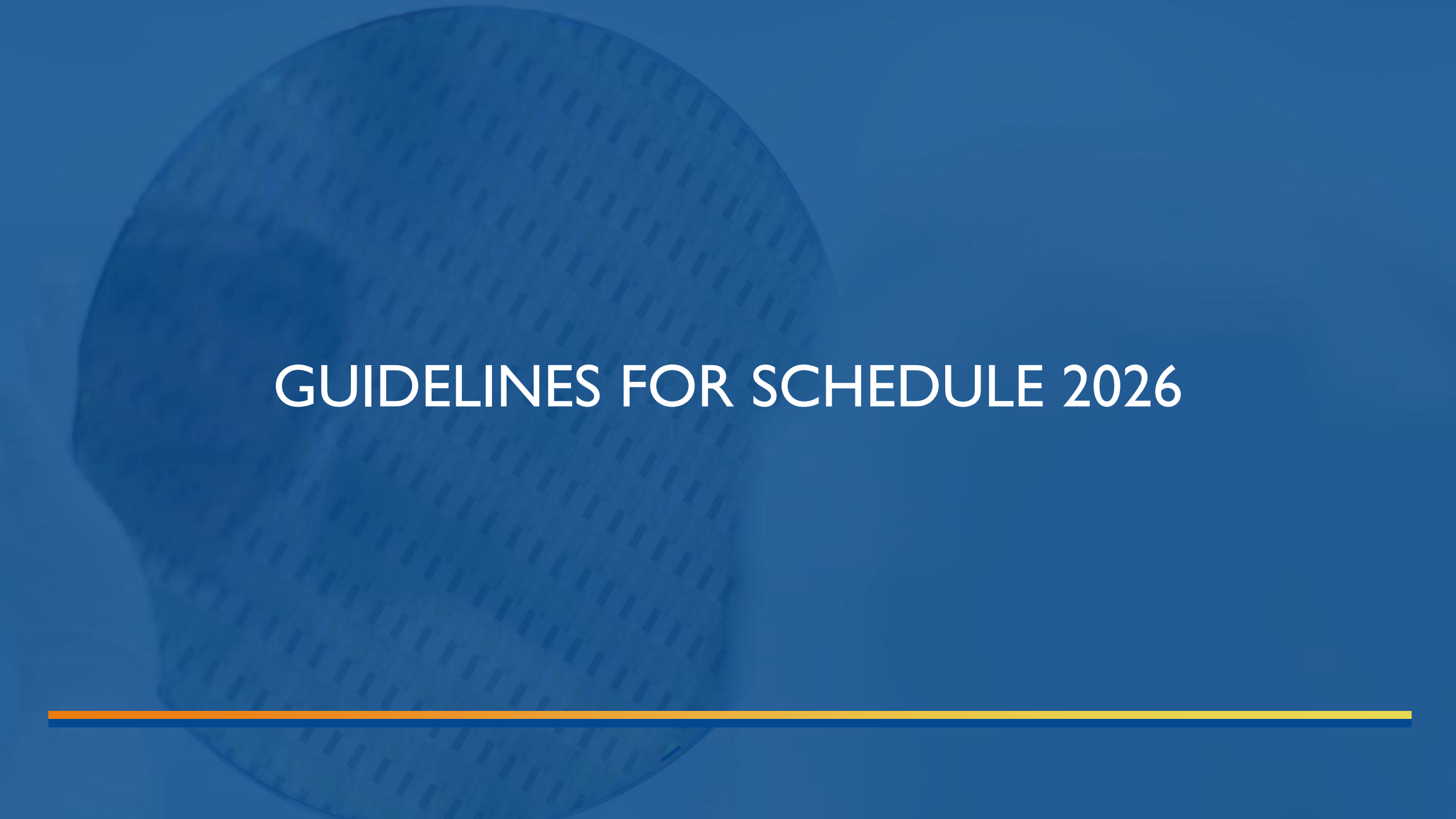
Mini@sic RUN SCHEDULE 2026 – 16nm, 28nm, 40nm

Technology	Month	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS**	Tape-out	Estimated shipment date*
16nm RF FinFET Compact (0.8/1.8V)	April	I0084	TMWB79	14	Dec 23 (2025)	Feb 6	Feb 24	Mar 24	Apr 7	Jul 1
	November	I0085	TMWB83	14	Aug 3	Oct 1	Oct 19	Nov 16	Nov 30	Feb 23 (2027)
28nm RF HPC Plus (0.9/1.8V, 0.9/2.5V)	March	I0065	TMWB62	15	Nov 25 (2025)	Jan 2	Feb 4	Feb 17	Mar 3	May 24
	May	I0066	TMWB63	15	Jan 26	Mar 6	Apr 8	Apr 21	May 5	Jul 26
	June	I0067	TMWB64	15	Feb 25	Apr 3	May 6	May 19	Jun 2	Aug 23
	August	I0068	TMWB65	15	Apr 27	Jun 12	Jul 15	Jul 28	Aug 11	Nov 1
	November	I0069	TMWB67	15	Aug 3	Sep 11	Oct 14	Oct 27	Nov 10	Jan 31 (2027)
40nm Logic 40LP (1.1/1.8V, 1.1/2.5V) Mixed-Signal/RF 40LP (1.1/1.8V, 1.1/2.5V)	April	I0055	TMWB52	12	Dec 23	Feb 12	Mar 02	Mar30	Apr 13	Jun 24
	October	I0056	TMWB57	14	Jun 30	Aug 13	Aug 31	Sep 28	Oct 12	Dec 23

Mini@sic RUN SCHEDULE 2026 – 65nm ~ 0.13nm

Technology	Month	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS**	Tape-out	Estimated shipment date*
65nm CMOS Logic or MS/RF, GP or LP	March	I0038-LP	TMWB40	I4	Nov 25 (2025)	Jan 9	Feb 11	Feb 24	Mar 10	May 22
	April	I0039-GP	TMWB41	I2	Dec 23	Feb 20	Mar 25	Apr 7	Apr 21	Jul 3
	June	I0040-LP	TMWB43	I2	Feb 25	Apr 17	May 20	Jun 2	Jun 16	Aug 28
	July	I0041-LP	TMWB44	I4	Mar 25	May 22	Jun 24	Jul 7	Jul 21	Oct 2
	September	I0042-LP	TMWB45	I4	May 25	Jul 17	Aug 19	Sep 1	Sep 15	Nov 27
	October	I0043-GP	TMWB46	I2	Jun 30	Aug 21	Sep 23	Oct 6	Oct 20	Jan 3 (2027)
	November	I0044-LP	TMWB47	I4	Aug 3	Sep 18	Oct 21	Nov 3	Nov 17	Jan 29 (2027)
0.13µm C High Voltage BCD Plus (1.5/3.3/5/10/12/16/20/24/28/36/VG1.5/3.3/5 V)	April	I0025	TMWB33	I2	Dec 23	Feb 13	Mar 03	Mar 31	Apr 14	Jun 18
	November	I0028	TMWB36	I4	Aug 3	Sep 18	Oct 06	Nov 03	Nov 17	Jan 21 (2027)

GUIDELINES FOR SCHEDULE 2026

The background features a large, semi-transparent blue sphere with a fine, grid-like texture on the left side. A horizontal line, composed of an orange top segment and a yellow bottom segment, spans the width of the page near the bottom.

- Single reservation for multiple chips
- No backup reservation
- Provide single GDS with all designs,
 - ▶ Enclosed with TSMC searing + 80um scribe (post-shrink if applicable).
 - ▶ If designs are not identical, put marker in the scribe line.
 - ▶ Add dummies to the scribe line for 12-inch tape-outs.
 - ▶ Exception: multiple reservations accepted for different projects with different metal stacks or far backend.

- The estimated shipment date is applicable for reservations with quantity <200 dies.
- If additional samples are required, additional cycle time of (1~3 weeks) might be needed.
- Cycle time estimates are based on typical conditions. Corner wafers or SHDMiM processing requires additional cycle time.
- Optional services adding cycle time
 - ▶ Lead free & copper bumping: 4 days
 - ▶ Extra wafer thinning (thinner than 10mils): up to 12 days
 - ▶ Additional bumped wafer thinning and die saw (each 200 ea.): 5 working days

- To ensure timely inclusion in the TSMC MPW when an IP merge is required, deliver the final GDS 2 weeks in advance to allow sufficient time for integration and validation.
- Why This Matters:
 - ▶ **Complete LVS Setup Required**
A fully validated LVS setup must be in place before initiating the merge process.
 - ▶ **Ip-transfer**
Third-party IPs have to be transferred from the vendor to the TSMC merge team, which may introduce delays in the process.
 - ▶ **Increased Complexity with Multiple IP Instances**
Merging several IP blocks adds significant complexity and increases the risk of integration issues.
 - ▶ **Merge Errors Can Jeopardize the Deadline**
Errors discovered after merging may delay the process and reduce the likelihood of meeting the MPW schedule. TSMC requests to re-submit the merge even for minor typos or missing files

Contact our teams through a portal support case:

Support Tape-out For support on the tape-out submission

Support SalesOps For support on portal, quotations, export documents, purchase orders, and design registration questions

Support EP packaging For any question related to the Europractice packaging offer.

Support Foundry For support on foundry libraries, PDK's (installation, flavors, bugs, ...), LVS

- October 24, 2025: Release of v1.0 2025
- November 21, 2025
 - ▶ Release of v1.0 2025
 - ▶ Clarification cycle time information slide 8



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